

ABSTRACT OF THE DISCLOSURE

A method of fabricating a transmit/receive (T/R) module utilizing low temperature co-fired ceramic (LTCC) material in place of high temperature co-fired ceramic (HTCC) material and utilizing a combination of multiple lamination steps which also include forming a ceramic frame, as opposed to a metal ring frame, in the process. Brazing metallization is also utilized to attach heat sinks and lids as well as pin connectors. The formation of the pin connectors is provided on the side surface of the T/R module with a side printing process.